Research Association
Molded Interconnect Devices 3-D MID e.V.

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Member of the
Arbeitsgemeinschaft
industrieller
Forschungsvereinigungen e.V.

MID-Award

The Research Association
Molded Interconnect Devices 3-D MID e.V.

Announcement 2021

1 Preamble

The Research Association for Molded Interconnect Devices 3-D MID e.V. awards the *MID Award* to graduates of universities for groundbreaking scientific work on MID technology. The prize is endowed with a certificate and 1.000,- €.

Molded Interconnect Devices (MID) are structured metallized basic bodies with integrated conductors. The high degree of design freedom with regard to shaping and structured metallization opens up a wide range of potential for the manufacture of highly integrated mechatronic products. The non-profit research association 3-D MID e.V. was founded in autumn 1992 to promote and develop this technology. Members are currently 73 companies and 32 university and research institutes from all MID-relevant fields.

2 Awarding guidelines

The MID Award of the Research Association is awarded to graduates of universities who have done outstanding scientific work in the field of MID technology. This includes in particular the following areas:

1 **Innovations in MID:**
Integrative product concepts; economic aspects; market development

2 **MID – Application and realisation:**
Extended benefits through MID; selection of MID production processes; strategies for successful MID projects

3 **Integrated CAD/CAM-systems:**
Development Systems ECAD/MCAD; 3D-MID-layout and design; Simulation

4 **Materials for MID:**
Use of new substrates; circuit carrier surfaces; connection media

5 **Manufacturing process:**
Plastics processing; metallization processes; structuring of conductor paths

6 **Packaging and connection technology:**
Mounting: SMT, THT, Chip on MID; alternative soldering methods, conductive bonding; System solutions for MID

7 **Quality assurance:**
Quality assurance measures; environmental protection, recycling; testing methods, standards

8 **Future developments:**
Printing technologies; alternative assembly technologies; rapid prototyping/manufacturing

The contributions should be scientific papers of the last 2 years accepted by the faculties and departments of the universities. Each paper to be submitted must be accompanied by an expert opinion from the supervising professor.

3 Call for applications for the award

Proposals can only be submitted by the supervising professors. The following documents must be enclosed with the proposals:

- Scientific work
- Expert opinion by the respective university lecturer
- Curriculum vitae of the applicant

The closing date for submission is Friday 6th November 2021.

4 Selection of the award-winning works

The submitted work will be advised and evaluated by the research advisory board of the research association 3-D MID e.V. The notification of the award winners will be made until December 1st, 2021. The *MID Award* of the Research Association will be awarded during the 14th International Congress Molded Interconnect Devices 2021 from February 9th to 10th 2021 in Amberg.

5 Submission and queries

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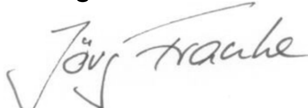

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